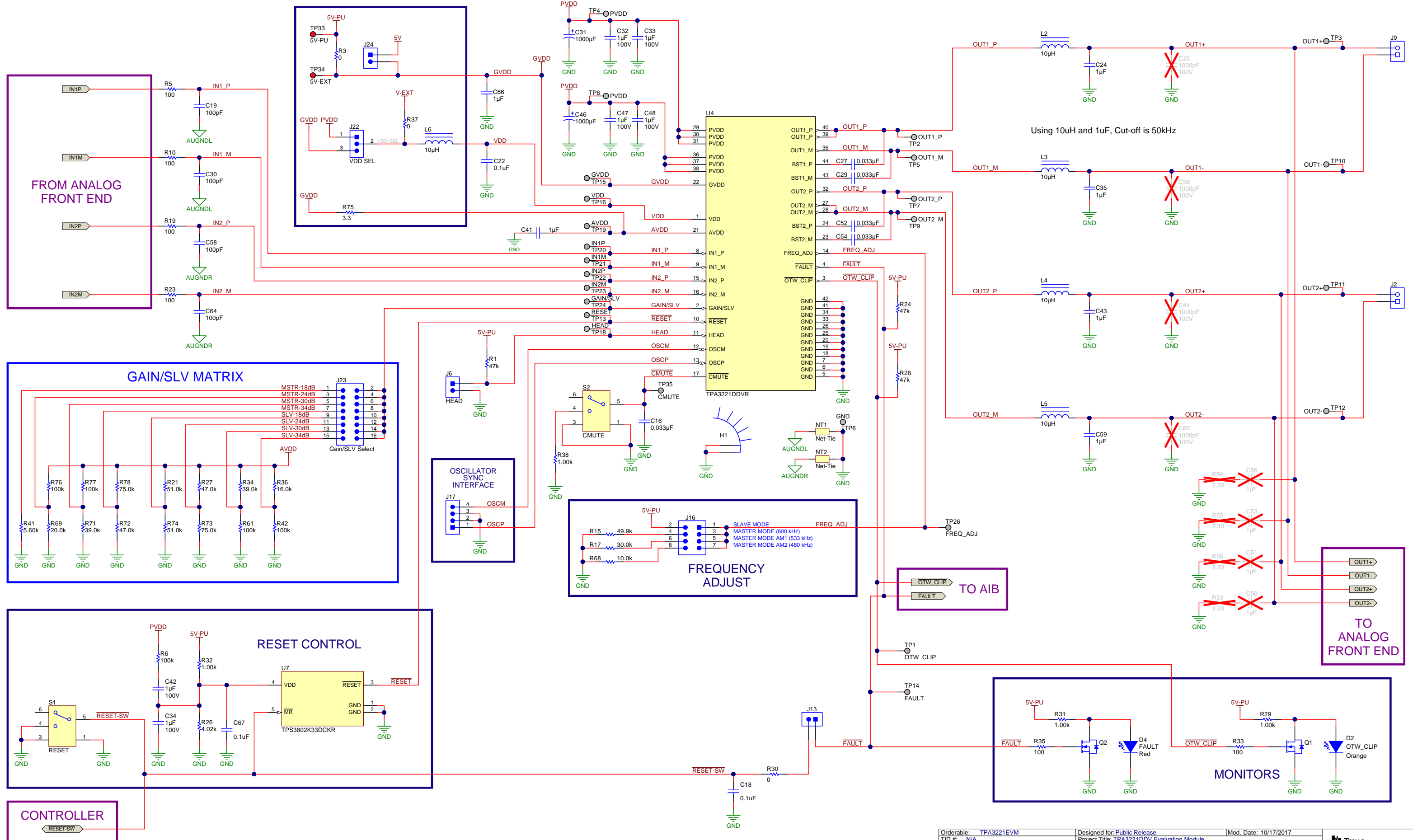


Orderable: TPA3221EVM	Designed for: Public Release	Mod. Date: 10/17/2017
TID #: N/A	Project Title: TPA3221DDV Evaluation Module	
Number: AMPS005	Rev: A	Sheet Title: ANALOG MUXES
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 1 of 4
Drawn By: LDN	File: AMPS005A_ANA-MUX.SchDoc	Size: B
Engineer: ADAM SIDELSKY	Contact: http://www.ti.com/support	

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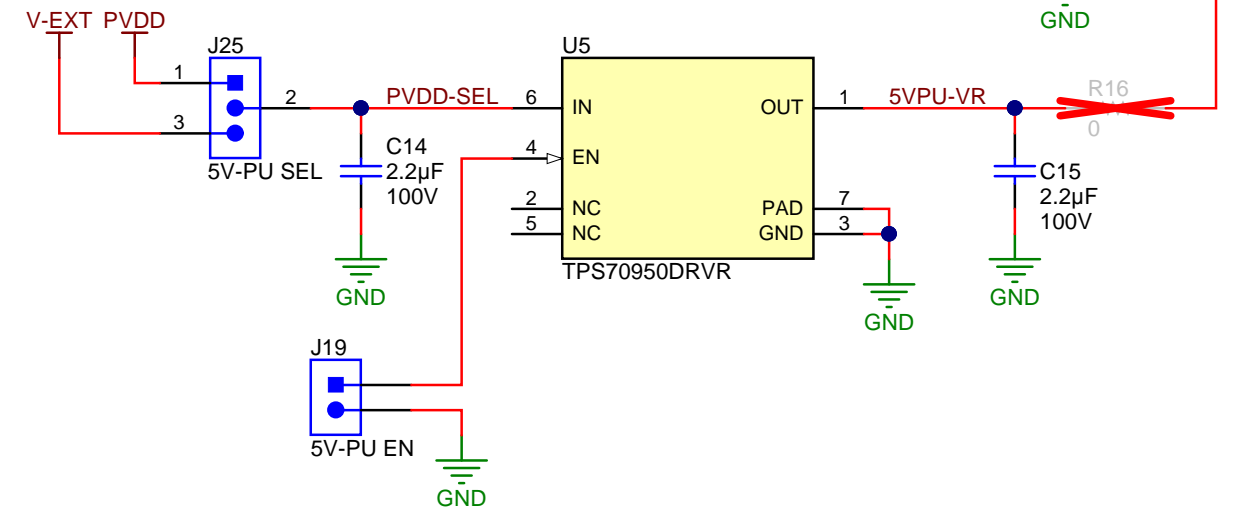
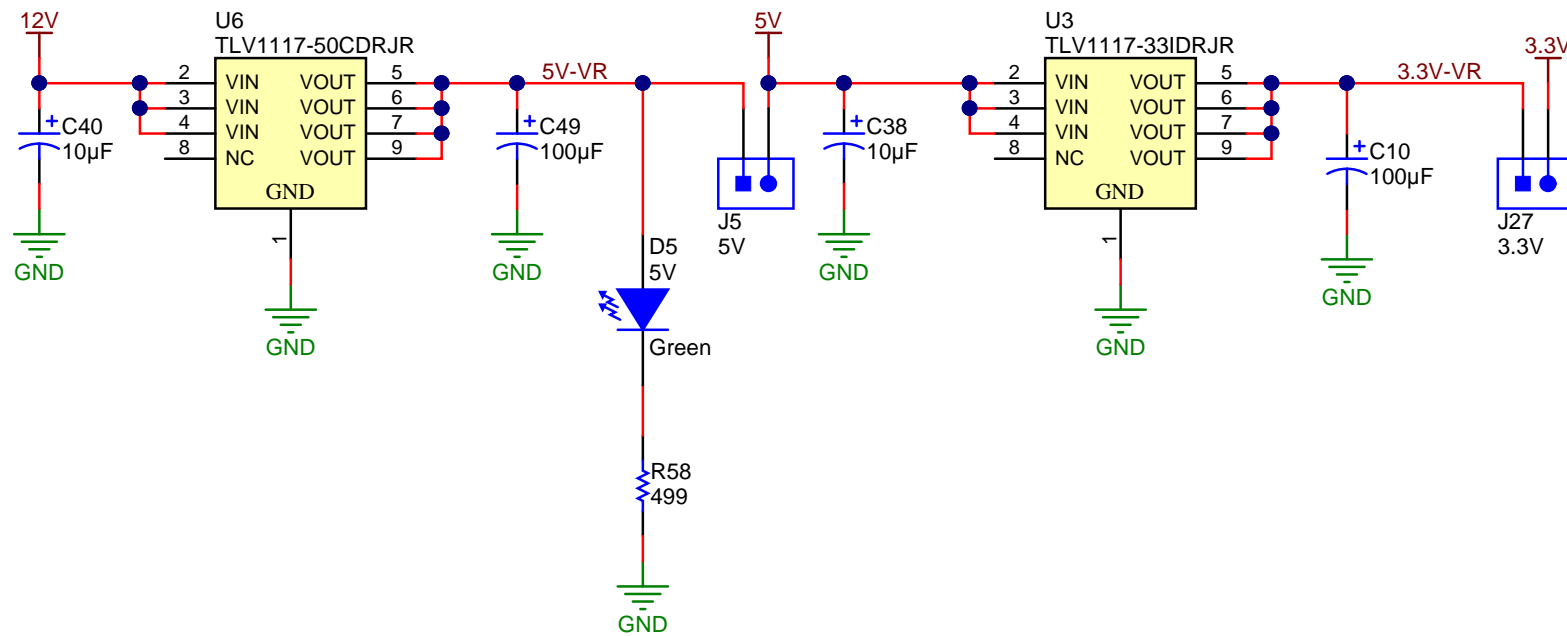
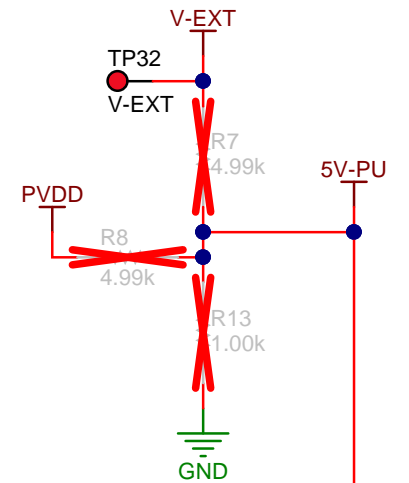
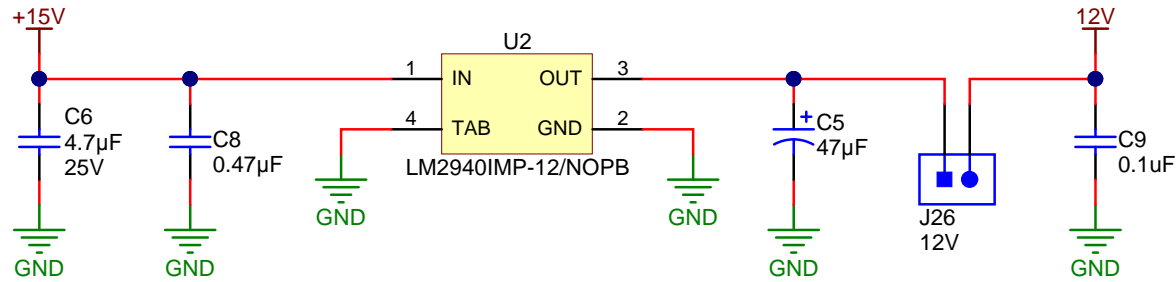
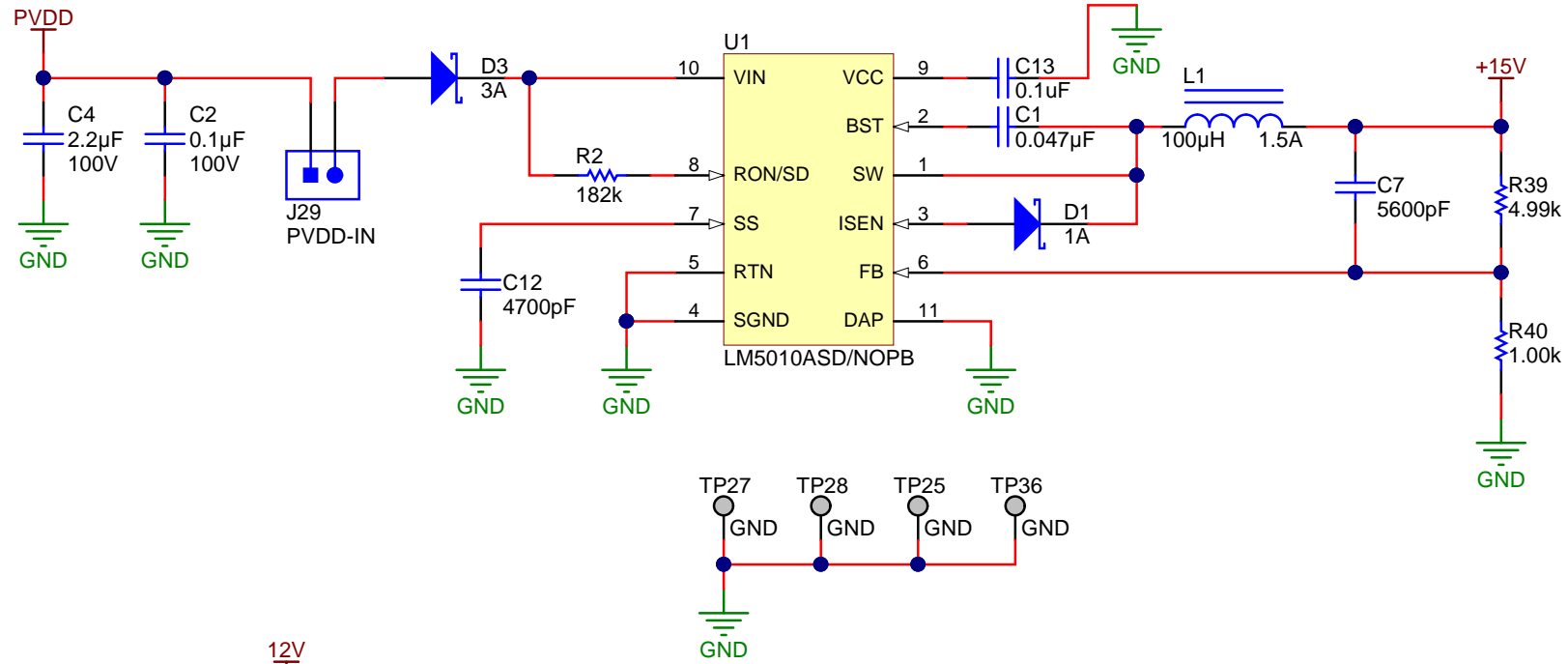
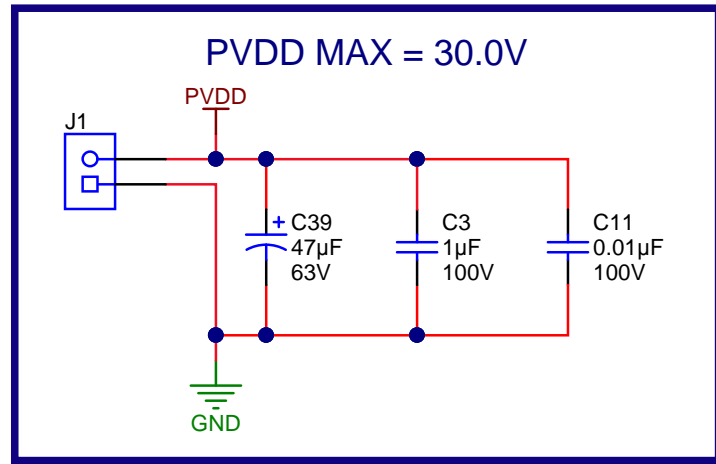


Orderable: TPA3221EVM	Designed for: Public Release	Mod. Date: 10/17/2017
TID #: N/A	Project Title: TPA3221DDV Evaluation Module	
Number: AMPS005	Sheet Title: TPA3221DDV I/O	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 4
Drawn By: LDN	File: AMPS005A_TPA3221-I/O_SchDoc	Size: BC
Engineer: ADAM SIDELSKY	Contact: http://www.ti.com/support	Rev: A

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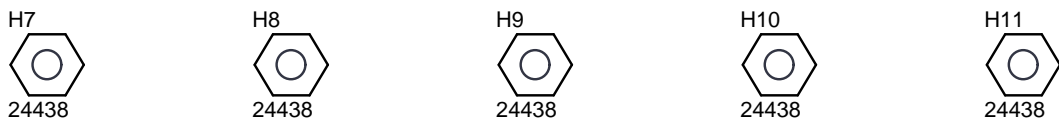
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 Sheet: 3 of 4
 Number: AMP5005
 SVN Rev: Version control disabled
 Drawn By: LDN
 Engineer: ADAM SIDELSKY

Designed for: Public Release
 Project Title: TPA3221DDV Evaluation Module
 Sheet Title: POWER SUPPLIES
 Assembly Variant: 001
 File: AMP5005A_PowerSupplies.SchDoc
 Contact: <http://www.ti.com/support>

TID #: N/A
 Mod. Date: 10/16/2017
 Size: AB
 Rev: A





PCB Number: AMPS005
PCB Rev: A

PCB LOGO
Texas Instruments

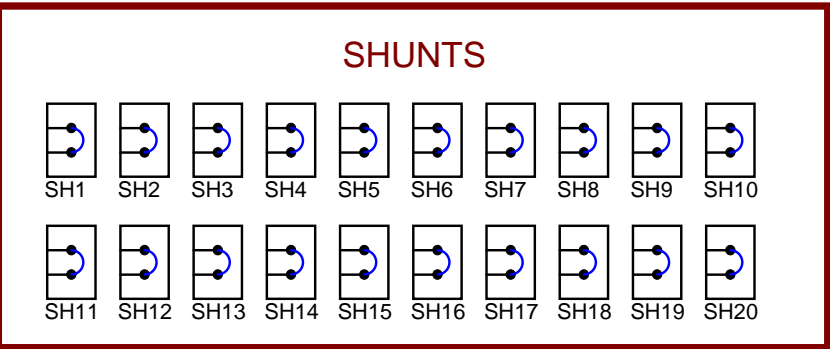
PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

ZZ1
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ2
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ3
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.



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Orderable: TPA3221EVM	Designed for: Public Release	Mod. Date: 10/16/2017
TID #: N/A	Project Title: TPA3221DDV Evaluation Module	
Number: AMPS005	Rev: A	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 4 of 4
Drawn By:	File: AMPS005A_EVM_Hardware.SchDoc	Size: Letter
Engineer: ADAM SIDELSKY	Contact: http://www.ti.com/support	

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